

Dual N-Channel MOSFET

General Description

The WSD3046DN33 is the highest performance trench Dual N- Channel MOSFET with extreme high cell density, which provide excellent $R_{DS(ON)}$ and gate charge for most of the synchronous buck converter applications.

The WSD3046DN33 meet the RoHS and Green Product requirement 100% E_{AS} guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% E_{AS} Guaranteed
- Green Device Available

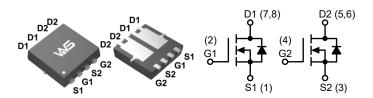
Product Summery

BV _{DSS}	R _{DS(ON)}	I _D		
30V	9mΩ	32A		

Applications

- POL Applications
- MB / VGA / Vcore
- Load Switch
- SMPS 2nd SR

DFN3X3-8L Pin Configuration



Absolute Maximum Ratings (T_A=25°C, Unless Otherwise Noted)

Symbol	Parameter		rameter Rating		
V _{DS}	Drain-Source Voltage		30	V	
V_{GS}	Gate-Source Voltage		±20	V	
I _D	Drain Current (Continuous) 1,3	T _C =25°C	32		
		T _C =100°C	20	Α	
I _{DM}	Drain Current (Pulse) ²		135		
P _D	Power Dissipation	T _C =25°C	26	W	
E _{AS}	Single Pulse Avalanche Energy		12	mJ	
T _{STG}	Storage Temperature Range		-55 to 150	°C	
TJ	Operating Junction Temperature Range		-55 to 150		

Thermal Data

Symbol	Parameter	Тур.	Max.	Units	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62	°C/\\	
$R_{ heta JC}$	Thermal Resistance, Junction-to-Case	3.6 C/V		°C/W	



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Electrical Characteristics (T_A=25°C, Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units	
Static							
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250μA	30			V	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V , V _{GS} =0V			1.0	μA	
I _{GSS}	Gate Leakage Current	V _{DS} =0V , V _{GS} =±20V			±100	nA	
On Characte	ristics						
V _{GS(th)}	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_{DS}=250\mu A$	1.0	1.5	2.5	V	
Б		V _{GS} =10V , I _D =15A		9	11		
$R_{DS(ON)}$	Drain-Source On-state Resistance	V _{GS} =4.5V , I _D =15A		13	15	mΩ	
g _{fs}	Forward Transconductance	V _{DS} =5V , I _D =5A		6		S	
Switching							
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f = 1.0MHz		3.0		Ω	
Q _g	Total Gate Charge			22		nC	
Q_{gs}	Gate-Source Charge	V _{GS} =10V , V _{DS} =15V , I _D =5A		4			
Q _{gd}	Gate-Drain Charge	_		6			
T _{d(on)}	Turn-On Delay Time			5		- ns	
T _r	Rise Time	7 V _{GS} =10V , V _{DD} =15V ,		3			
T _{d(off)}	Turn-Off Delay Time	$I_D=1A$, $R_G=6\Omega$		14			
T _f	Fall Time			8			
Dynamic							
C _{iss}	Input Capacitance			1050			
C _{oss}	Output Capacitance	V _{GS} =0V , V _{DS} =15V , f = 1.0MHz		125		pF	
C _{rss}	Reverse Transfer Capacitance			100			
Drain-Source Diode Characteristics and Maximum Ratings							
I _S	Continuous Source Current	V V 0V 5			32	,	
I _{SM}	Pulsed Source Curren ³	V _G =V _D =0V , Force Current			90	A	
V _{SD}	Diode Forward Voltage	I _{SD} =1A , V _{GS} =0V			1.2	V	

Note:

- 1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
- 2. V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =16A, R_{G} =25, Starting T_{J} =25°C.
- 3. The data tested by pulsed , pulse width $\leq 300 \mu s$, duty cycle $\leq 2\%.$
- 4. Essentially independent of operating temperature.



Typical Characteristics

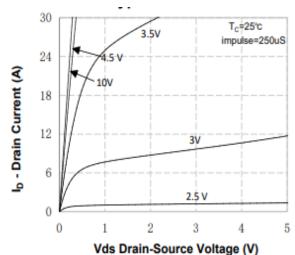


Figure 1. On-Region Characteristics

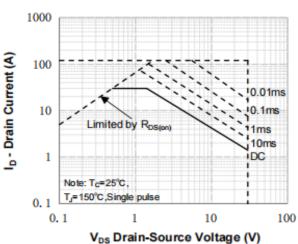


Figure 3. Maximum Safe Operating Area

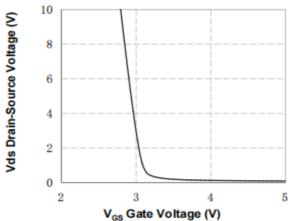


Figure 5. Vds Drain-Source Voltage vs Gate Voltage

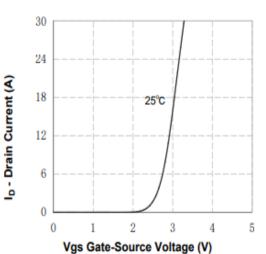


Figure 2. Transfer Characteristics

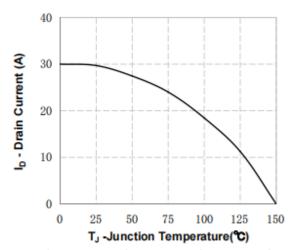
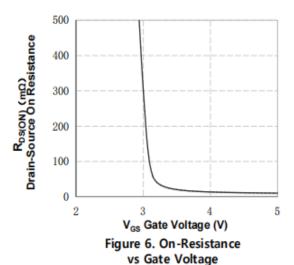


Figure 4. Maximum Continuous Drain Current vs Temperature







Typical Characteristics (Cont.)

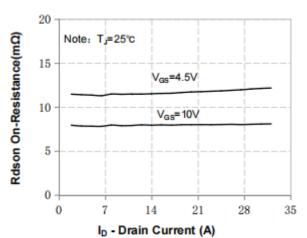
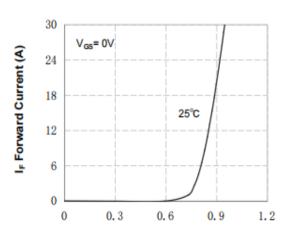
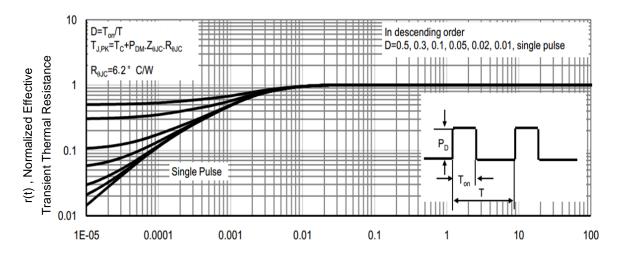


Figure 7. On-Resistance Variation vs Drain Current and Gate Voltage



V_F,Forward Voltage [V] Figure 8. Body Diode Forward Voltage Variation vs Source Current



T1, Square Wave Pulse Duration(sec)

Fig9. T1 ,Transient Thermal Response Curve

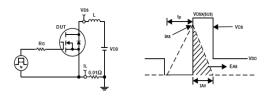


Fig10. Unclamped Inductive Test Circuit and waveforms

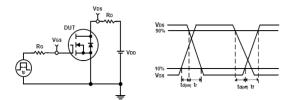
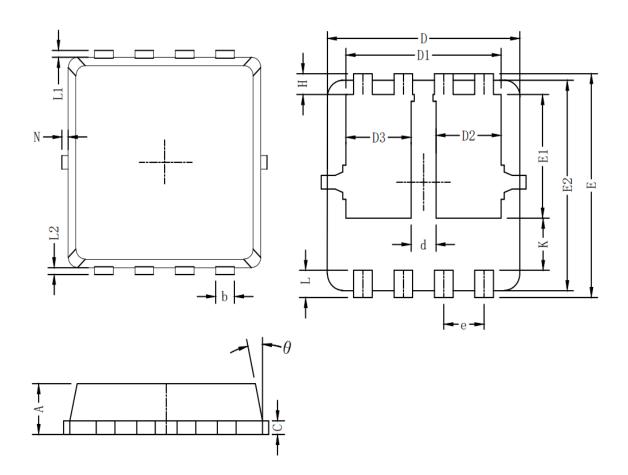


Fig11. Switching Time Test Circuit and waveforms





Packaging information



Symbol	Dim in mm			
Symbol	min	typ	max	
А	0.6	0.75	0.9	
b	0.2	0.3	0.4	
С	0.15	0.2	0.25	
D	3	3.1	3.2	
D1	2.3	2.45	2.6	
D2/D3	0.8	1	1.2	
E	3.15	3.3	3.45	
E1	1.43	1.73	1.93	
E2	2.9	3.05	3.2	
е	0.65BSC			
Н	0.2	0.35	0.5	
K	0.57	0.77	0.87	
L	0.3	0.4	0.5	
L1/L2	0.1REF			
θ	8°	10°	13°	
N	0		0.15	
d	0.3	0.4	0.5	



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